

| V _{DSS} | 600V |
|----------------------------|--------|
| R _{DS(on)} (Max.) | 0.104Ω |
| I _D | ±42A |
| P _D | 495W |

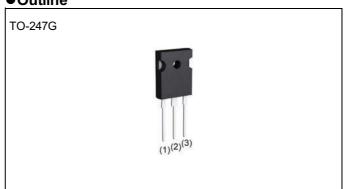
Features

- 1) Fast reverse recovery time (trr)
- 2) Low on-resistance
- 3) Fast switching speed
- 4) Drive circuits can be simple
- 5) Pb-free plating; RoHS compliant

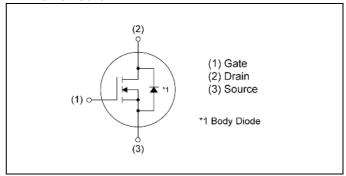
Application

Switching applications

Outline



•Inner circuit



Packaging specifications

| Packing | Tube |
|---------------------------|-----------|
| Packing code | C13 |
| Marking | R6042JNZ4 |
| Basic ordering unit (pcs) | 600 |

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

| Parameter | Symbol | Value | Unit |
|--|--------------------|-------------|------|
| Drain - Source voltage | V _{DSS} | 600 | V |
| Continuous drain current (T _c = 25°C) | I _D *1 | ±42 | Α |
| Pulsed drain current | I _{DP} *2 | ±126 | Α |
| Gate - Source voltage | V _{GSS} | ±30 | V |
| Avalanche current, single pulse | I _{AS} *3 | 8.9 | Α |
| Avalanche energy, single pulse | E _{AS} *3 | 871 | mJ |
| Power dissipation (T _c = 25°C) | P _D | 495 | W |
| Junction temperature | T _j | 150 | °C |
| Operating junction and storage temperature range | T _{stg} | -55 to +150 | °C |

●Thermal resistance

| Downwoodow | O | Values | | | 1.1:4 |
|--|-------------------|--------|------|------|-------|
| Parameter | Symbol | Min. | Тур. | Max. | Unit |
| Thermal resistance, junction - case | R _{thJC} | - | - | 0.25 | °C/W |
| Thermal resistance, junction - ambient | R _{thJA} | - | - | 30 | °C/W |
| Soldering temperature, wavesoldering for 10s | T _{sold} | - | - | 265 | °C |

• Electrical characteristics $(T_a = 25^{\circ}C)$

| Darameter | Cumb al | Conditions | Values | | | Unit |
|---|------------------------|---|--------|-------|-------|-------|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Offic |
| Drain - Source breakdown voltage | V _{(BR)DSS} | V _{GS} = 0V, I _D = 1mA | 600 | - | - | V |
| Zero gate voltage drain current | I _{DSS} | $V_{DS} = 600V, V_{GS} = 0V$ $T_j = 25^{\circ}C$ | - | - | 100 | μA |
| Gate - Source leakage current | I _{GSS} | $V_{GS} = \pm 30 V, V_{DS} = 0 V$ | - | - | ±100 | nA |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_{D} = 5.5 \text{mA}$ | 5.0 | 6.0 | 7.0 | V |
| Static drain - source on - state resistance | R _{DS(on)} *5 | $V_{GS} = 15V, I_D = 21A$ $T_j = 25^{\circ}C$ | - | 0.080 | 0.104 | Ω |
| Gate resistance | R_{G} | f = 1MHz, open drain | - | 1.2 | - | Ω |

● Electrical characteristics (T_a = 25°C)

| Dovometer | Cumphal | Conditions | Values | | | Unit |
|---|--------------------------|---------------------------------------|--------|------|------|------|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Unit |
| Input capacitance | C _{iss} | V _{GS} = 0V | - | 3500 | - | |
| Output capacitance | C _{oss} | V _{DS} = 100V | - | 200 | - | |
| Reverse transfer capacitance | C _{rss} | f = 1MHz | - | 2.5 | - | _ |
| Effective output capacitance energy related | C _{o(er)} *6 | V _{GS} = 0V | - | 145 | - | pF |
| Effective output capacitance time related | C _{o(tr)} *7 | V _{DS} = 0V to 480V | - | 600 | - | |
| Turn - on delay time | t _{d(on)} *5 | $V_{DD} \simeq 300V$, $V_{GS} = 15V$ | - | 40 | - | |
| Rise time | t _r *5 | I _D = 21A | 1 | 30 | - | no |
| Turn - off delay time | t _{d(off)} *5 | $R_L \simeq 14.3\Omega$ | - | 100 | - | ns |
| Fall time | t _f *5 | $R_G = 10\Omega$ | - | 35 | - | |

● Gate charge characteristics (T_a = 25°C)

| Darameter | Cymabal | Conditions | Values | | | Linit |
|----------------------|------------------------|--|--------|------|------|-------|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Unit |
| Total gate charge | Q_g^{*5} | V _{DD} ≈ 300V | - | 100 | - | |
| Gate - Source charge | Q _{gs} *5 | I _D = 42A | - | 30 | - | nC |
| Gate - Drain charge | Q _{gd} *5 | V _{GS} = 15V | - | 35 | - | |
| Gate plateau voltage | V _(plateau) | V _{DD} ≈ 300V, I _D = 42A | - | 10.0 | - | V |

^{*1} Limited only by maximum temperature allowed.

^{*2} Pw \leq 10µs, Duty cycle \leq 1%

^{*3} L \simeq 50mH, V_{DD} = 50V, R_G = 25 Ω , starting T_i = 25°C

^{*4} Tc=25°C

^{*5} Pulsed

^{*6} Co(er) is a fixed capacitance that gives the same stored energy as Coss while V_{DS} is rising from 0 to 80% V_{DSS} .

^{*7} Co(tr) is a fixed capacitance that gives the same charging time as Coss while V_{DS} is rising from 0 to 80% V_{DSS} .

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

| Parameter | Cumbal | Conditions | Values | | | Unit | |
|-------------------------------|--------------------|---|--------|------|------|-------|--|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Offic | |
| Source current | I _S *1 | _ | | - | 42 | Α | |
| Pulsed source current | I _{SP} *2 | T _C = 25°C | 1 | - | 126 | Α | |
| Source-Drain voltage | V _{SD} *5 | $V_{GS} = 0V, I_{S} = 42A$ | - | - | 1.7 | V | |
| Reverse recovery time | t _{rr} *5 | | - | 110 | - | ns | |
| Reverse recovery charge | Q _{rr} *5 | I _S = 42A di/dt = 100A/μs | | 460 | - | nC | |
| Peak reverse recovery current | _{rr} *5 | | - | 8.5 | - | А | |

Fig.1 Power Dissipation Derating Curve

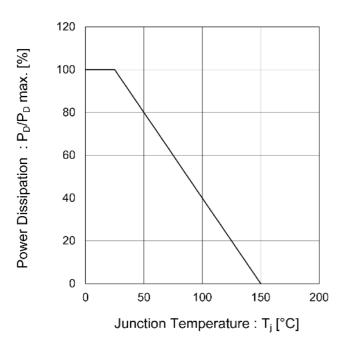


Fig.2 Drain Current Derating
Curve vs. Junction Temperature

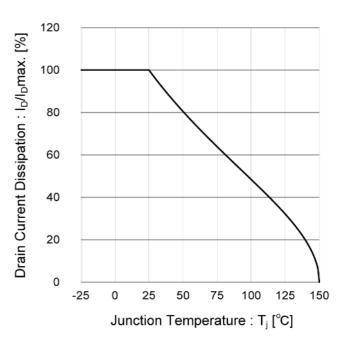


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

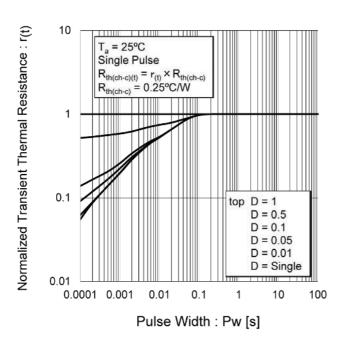


Fig.4 Maximum Safe Operating Area

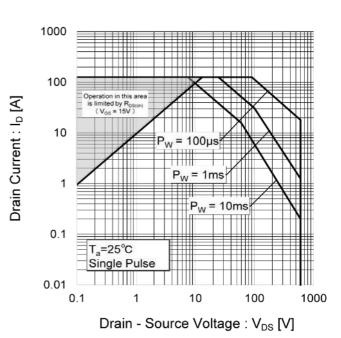


Fig.5 Avalanche Energy Derating
Curve vs. Junction Temperature

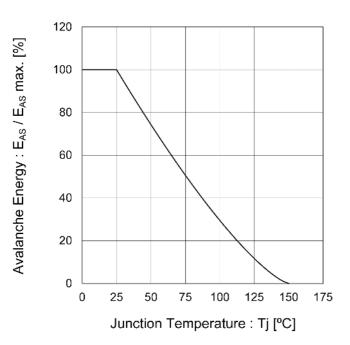


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

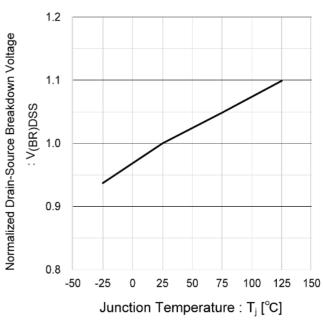


Fig.7 Typical Output Characteristics(I)

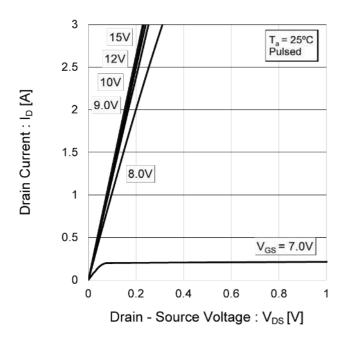
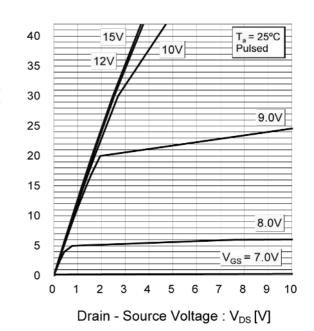


Fig.8 Typical Output Characteristics(II)



Drain Current : I_D [A]

Fig.9 Typical Transfer Characteristics

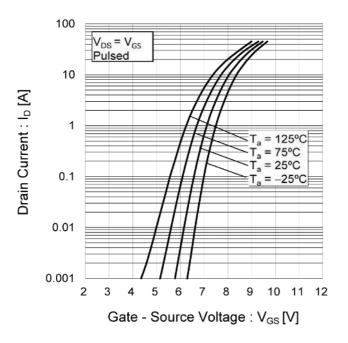


Fig.10 Normalized Gate Threshold .

Voltage vs Junction Temperature

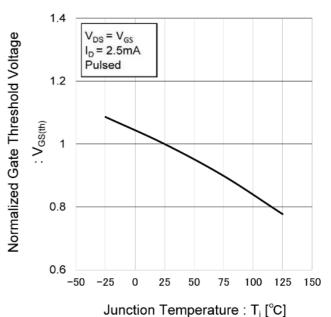


Fig.11 Static Drain - Source On - State Resistance vs. Gate Source Voltage

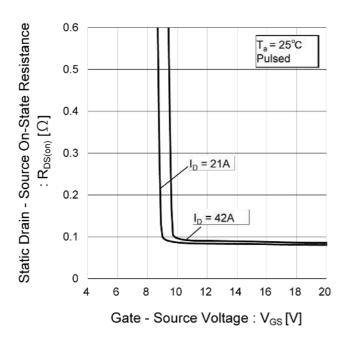


Fig.12 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

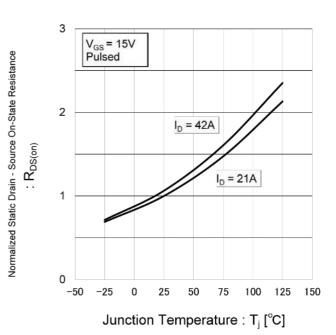


Fig.13 Static Drain - Source On - State Resistance vs. Drain Current(I)

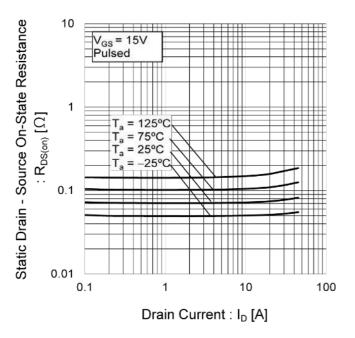


Fig.14 Typical Capacitance vs.

Drain - Source Voltage

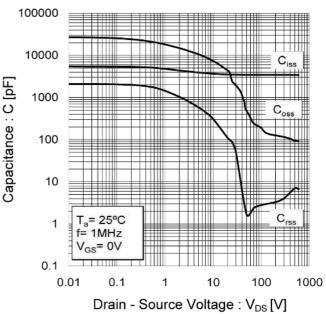


Fig.15 Typical Coss Stored Energy

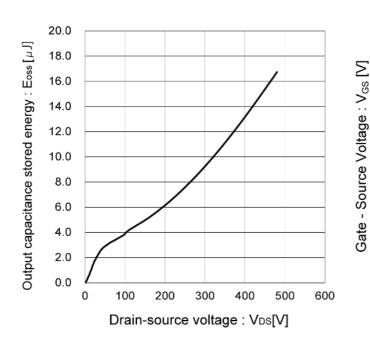


Fig.16 Dynamic Input Characteristics

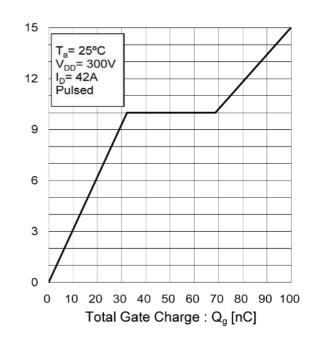


Fig.17 Inverse Diode Forward Current vs. Source - Drain Voltage

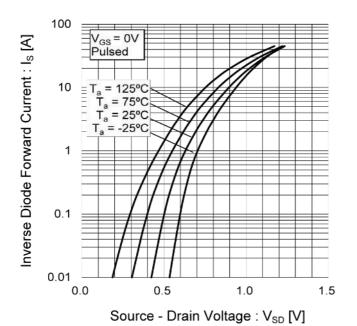
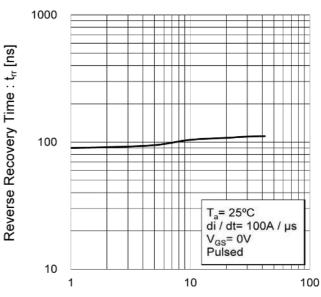


Fig.18 Reverse Recovery Time vs.
Inverse Diode Forward Current



Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

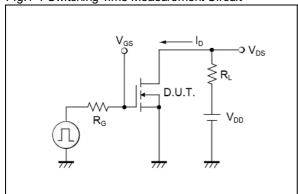


Fig.2-1 Gate Charge Measurement Circuit

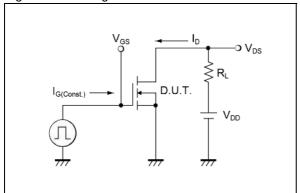


Fig.3-1 Avalanche Measurement Circuit

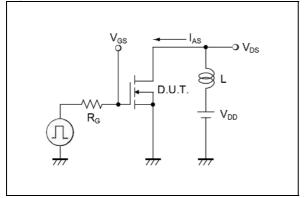


Fig.4-1 Diode Characteristice Measurement Circuit

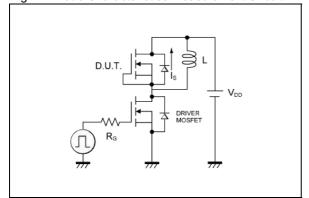


Fig.1-2 Switching Waveforms

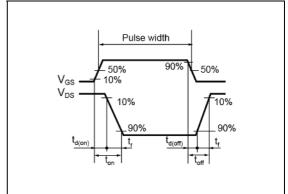


Fig.2-2 Gate Charge Waveform

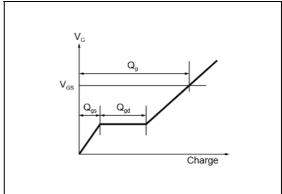


Fig.3-2 Avalanche Waveform

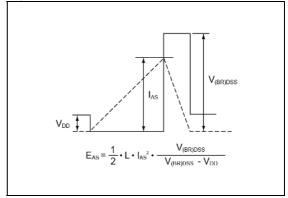
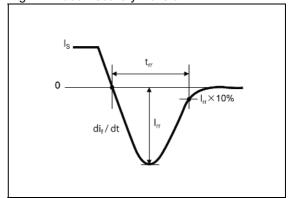
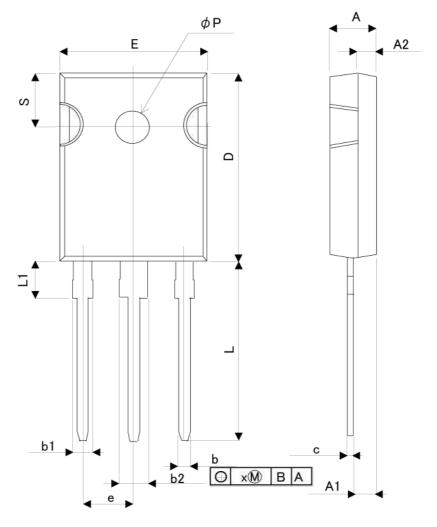


Fig.4-2 Diode Recovery Waveform



Dimensions

TO-247



| DIM | MILIMI | ETERS | INC | HES |
|-------|--------|-------|-------|-------|
| ואונט | MIN | MAX | MIN | MAX |
| Α | 4.82 | 5.22 | 0.190 | 0.206 |
| A1 | 2.11 | 2.71 | 0.083 | 0.107 |
| A2 | 1.80 | 2.20 | 0.071 | 0.087 |
| b | 1.00 | 1.40 | 0.039 | 0.055 |
| b1 | 1.80 | 2.20 | 0.071 | 0.087 |
| b2 | 2.80 | 3.20 | 0.110 | 0.126 |
| С | 0.45 | 0.75 | 0.018 | 0.030 |
| D | 20.65 | 21.25 | 0.813 | 0.837 |
| E | 15.64 | 16.24 | 0.616 | 0.639 |
| е | 5.4 | 14 | 0.2 | 14 |
| L | 19.77 | 20.37 | 0.778 | 0.802 |
| L1 | 4.09 | 4.29 | 0.161 | 0.169 |
| Р | 3.51 | 3.71 | 0.138 | 0.146 |
| S | 5.97 | 6.37 | 0.235 | 0.251 |

Dimension in mm/inches

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| JAPAN | USA | EU | CHINA |
|---------|----------|------------|----------|
| CLASSⅢ | CLASSⅢ | CLASS II b | CLASSIII |
| CLASSIV | CLASSIII | CLASSⅢ | CLASSIII |

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 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
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- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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